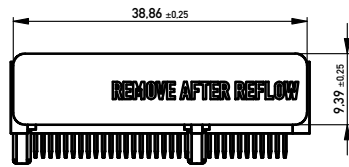
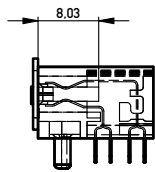


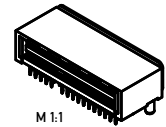
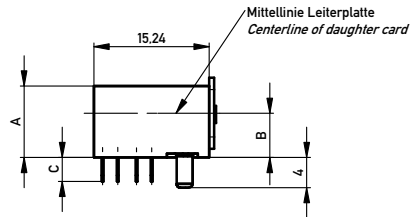
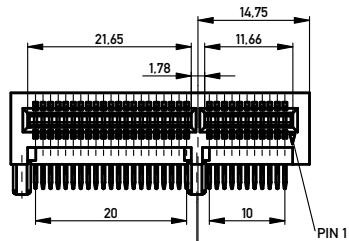
view with dust cover



Detail contact area

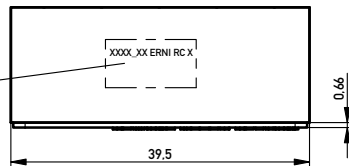


Offset von Führungssteg zu Referenzzapfen
Offset from guiding bar to reference peg 0.15



M 1:1

Datum
Date code (see notes)



NOTES:

Material: LCP GF 30 schwarz
Material: LCP GF 30 black

Galvanik: min. 1.27 µm Unternickelung
über gesamten PIN - Bereich
Gold - Flash im Lötbereich

Plating: min. 1.27 µm Ni entire contact
Gold - Flash plating on contact tails

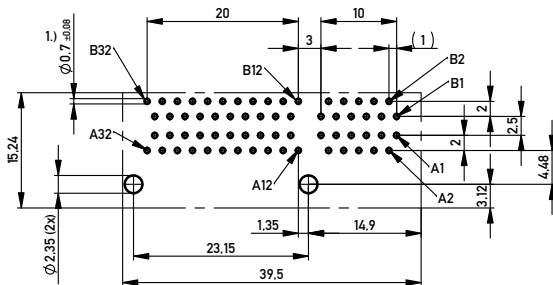
1.) Fertiglochdurchmesser
finished viadiameter (PTH)

Package: Tray (20 pcs.)

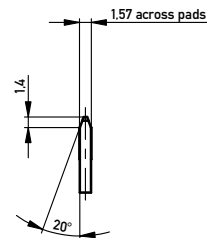
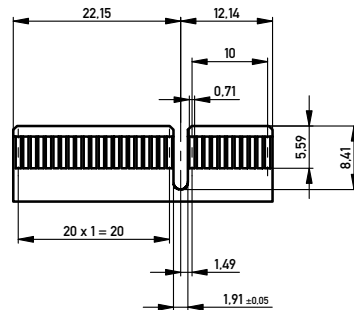
Connector printing / Labeling:
according to drawing 294775

| Resistance | Part No. | Length (mm) | Width (mm) | Height (mm) | Plating |
|------------|----------|-------------|------------|-------------|------------------|
| 85 Ohm | 009804 | 14,7 | 11,18 | 3,18 | min. 0.8 µm Au |
| | 009704 | 14,7 | 11,18 | 3,18 | min. 0.127 µm Au |
| | 009604 | 14,7 | 11,18 | 2,54 | min. 0.8 µm Au |
| | 009504 | 14,7 | 11,18 | 2,54 | min. 0.127 µm Au |
| | 009404 | 9,4 | 5,84 | 3,18 | min. 0.8 µm Au |
| | 009304 | 9,4 | 5,84 | 3,18 | min. 0.127 µm Au |
| | 009204 | 9,4 | 5,84 | 2,54 | min. 0.8 µm Au |
| | 009104 | 9,4 | 5,84 | 2,54 | min. 0.127 µm Au |
| | 100 Ohm | 009065 | 20,3 | 16,69 | 3,18 |
| 009064 | | 14,7 | 11,18 | 3,18 | min. 0.8 µm Au |
| 009063 | | 9,4 | 5,84 | 3,18 | min. 0.8 µm Au |
| 009045 | | 20,3 | 16,69 | 2,54 | min. 0.8 µm Au |
| 009044 | | 14,7 | 11,18 | 2,54 | min. 0.8 µm Au |
| 009043 | | 9,4 | 5,84 | 2,54 | min. 0.8 µm Au |
| 009025 | | 20,3 | 16,69 | 3,18 | min. 0.127 µm Au |
| 009024 | | 14,7 | 11,18 | 3,18 | min. 0.127 µm Au |
| 009023 | | 9,4 | 5,84 | 3,18 | min. 0.127 µm Au |
| 009005 | | 20,3 | 16,69 | 2,54 | min. 0.127 µm Au |
| 009004 | | 14,7 | 11,18 | 2,54 | min. 0.127 µm Au |
| 009003 | | 9,4 | 5,84 | 2,54 | min. 0.127 µm Au |

Lochbild für Leiterplatte (Bestückungsseite)
Board hole pattern (component mounting side)



daughter card layout



Layout proposal is in accordance with the PCI Express spezifikation

| | | | | | | | | | | | | | | | |
|---|---|--|---|----|-----|------|----|--------|-------|--|--------------------|--------------------|--------------------|---|--|
| Information / Tolerances: Sollern nicht anders angegeben / unless otherwise notes | Tolerances | Scale 2:1 | Designation Abgew. PCI Express STV 64pol. RT. Angle PCI Express 64 pins | | | | | | | | | | | | |
| | <table border="1"> <tr> <td>.x</td> <td>.xx</td> <td>.xxx</td> </tr> <tr> <td>±0</td> <td>±0.127</td> <td>±0.05</td> </tr> </table> | | | .x | .xx | .xxx | ±0 | ±0.127 | ±0.05 | <table border="1"> <tr> <td>Maß "A" Dim "A"</td> <td>Maß "B" Dim "B"</td> <td>Maß "C" Dim "C"</td> <td>Oberfläche Steckbereich plating contact area</td> </tr> <tr> <td></td> <td></td> <td></td> <td></td> </tr> </table> | Maß "A" Dim "A" | Maß "B" Dim "B" | Maß "C" Dim "C" | Oberfläche Steckbereich plating contact area | |
| .x | .xx | .xxx | | | | | | | | | | | | | |
| ±0 | ±0.127 | ±0.05 | | | | | | | | | | | | | |
| Maß "A" Dim "A" | Maß "B" Dim "B" | Maß "C" Dim "C" | Oberfläche Steckbereich plating contact area | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
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| g | 10.06.2014 |
| Index | Date |